



100% Material Declaration Data Sheet FT64

PK232 (v1.1) March 19, 2012

Average Weight: 0.2450g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.009338	3.81%
	Silicon (Si)	7440-21-3	99.96		0.009334	
	Aluminum	7429-90-5	0.04		0.000004	
Die Attach					0.001018	0.41%
	Silver (Ag)	7440-22-4	75.00		0.000764	
	Epoxy Cresol Novolak	29690-82-2	24.80		0.000252	
	Dibutyl Phthalate	84-74-2	0.20		0.000002	
Mold Compound					0.149487	61.01%
	Biphenyl epoxy resin	85951-11-6	12.00		0.017939	
	Phenol Resin	9003-35-4	7.00		0.010464	
	Quartz	14808-60-7	2.50		0.003737	
	Silica, vitreous	60676-86-0	77.00		0.115106	
	Carbon Black	1333-86-4	0.50		0.000747	
	Antimony Trioxide	1309-64-4	0.50		0.000747	
	Brominated Epoxy Resin	68541-56-0	0.50		0.000747	
Solder Balls					0.017586	7.18%
	Tin (Sn)	7440-31-5	63.00		0.011079	
	Lead (Pb)	7439-92-1	37.00		0.006507	
Gold Wire					0.000837	0.34%
	Gold (Au)	7440-57-5	100.00		0.000837	

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Substrate					0.066999	27.340
Coating	Copper (Cu)	7440-50-8	24.92		0.023527	
	Nickel (Ni)	7440-02-0	14.16		0.000195	
	Gold (Au)	7440-57-5	0.57		0.000119	
Core	Fiber Glass	65997-17-3	8.49		0.016694	
	Epoxy resin	9003-36-5	8.49		0.009485	
	Metal Hydroxide	21645-51-2	0.78		0.000379	
	Bismaleimide	105391-33-1	0.08		0.005691	
	Triazine	25722-66-1	0.24		0.005691	
Substrate	Baryum sulfate	7727-43-7	0.03		0.000522	
	Dipropylene glycol monomethyl	34590-94-8	3.27		0.000052	
	Talc containing no asbestiform fibers	14807-96-6	3.35		0.000164	
	Silica crystalline	14808-60-7	0.03		0.000023	
	2-(2-Ethoxyethoxy)ethyl Acetate	112-15-2	35.12		0.002192	
	Acrylates derivative	407-47-6	0.29		0.002244	
	amine compound	trade secret	1.78		0.000021	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/06/08	1.0	Initial Xilinx release.
03/19/12	1.1	Component CAS# update.

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